SOT1571-7

plastic, thermal enhanced low profile quad flat package; 48 leads; 0.5 mm pitch, 7 mm x 7 mm x 1.4 mm body

14 December 2017 **Package information**

1. Package summary

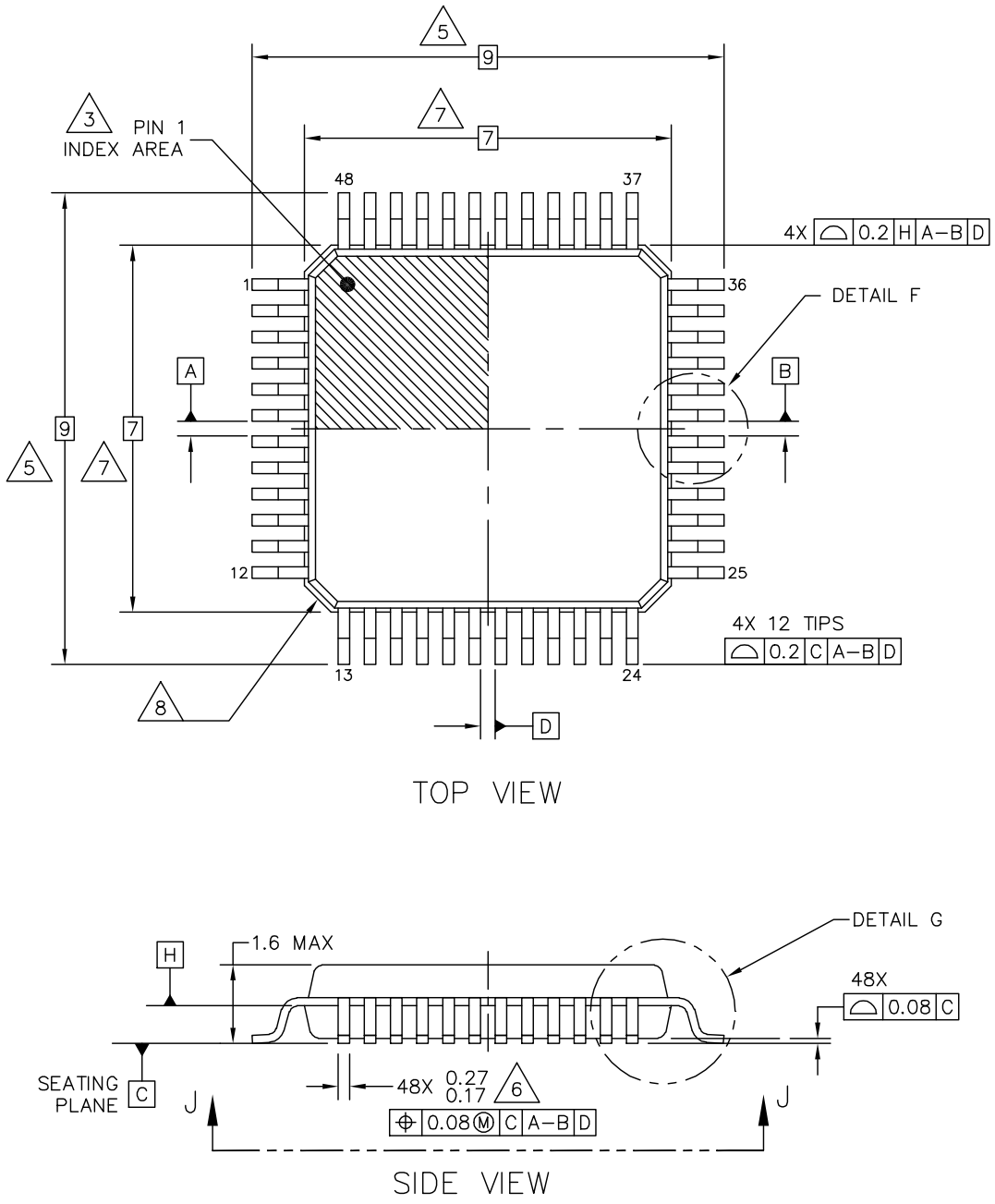
Terminal position code	Q (quad)
Package type descriptive code	HLQFP48
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
JEDEC package outline code	MS-026 BBC
Mounting method type	S (surface mount)
Issue date	28-8-2017
Manufacturer package code	98ASA01111D

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	7	-	mm
E	package width		-	-	7	-	mm
A_2	package height		-	-	1.4	-	mm
e	nominal pitch		-	-	0.5	-	mm
n_2	actual quantity of termination		-	-	48	-	A/A

plastic, thermal enhanced low profile quad flat package; 48 leads; 0.5 mm pitch, 7 mm x 7 mm x 1.4 mm body

2. Package outline

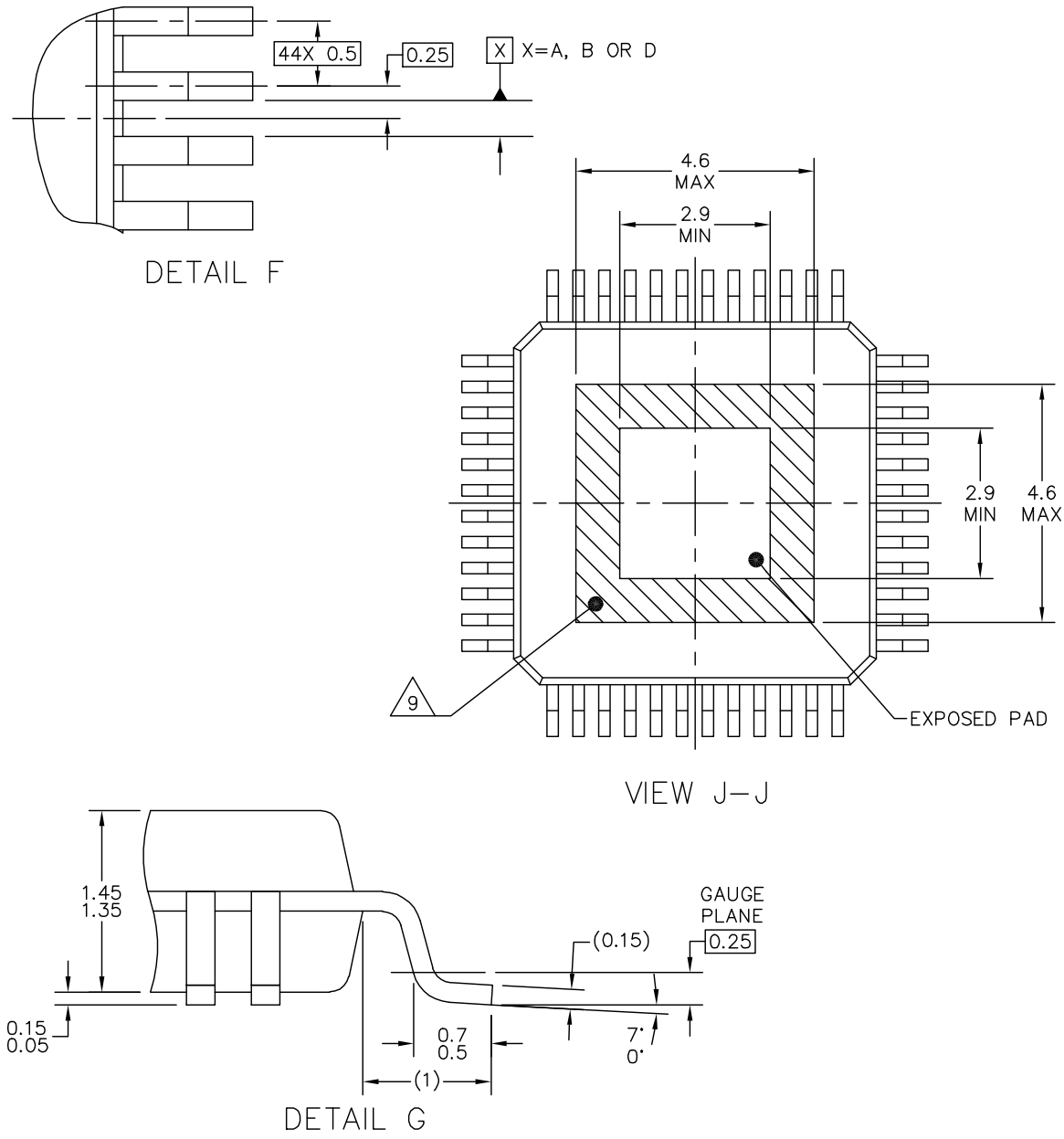


DATE: 28 AUG 2017

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: JEDEC MS–026 BBC	DRAWING NUMBER: SOT1571–7	REVISION: 0	

Fig. 1. Package outline SOT1571-7

plastic, thermal enhanced low profile quad flat package; 48 leads; 0.5 mm pitch, 7 mm x 7 mm x 1.4 mm body



DATE: 28 AUG 2017

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: JEDEC MS–026 BBC	DRAWING NUMBER: SOT1571–7	REVISION: O	

Fig. 2. Package outline dt HLQFP48 (SOT1571-7)

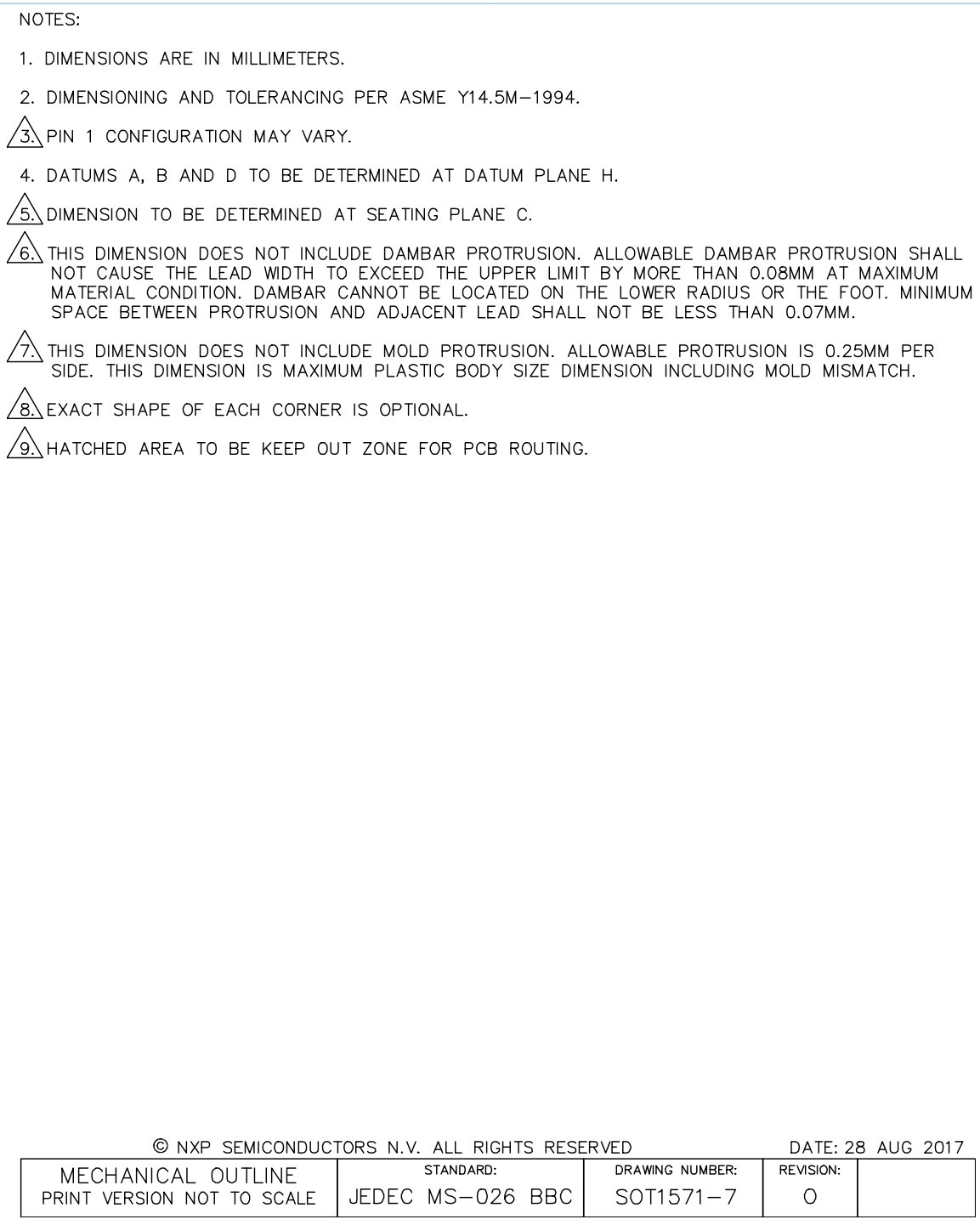
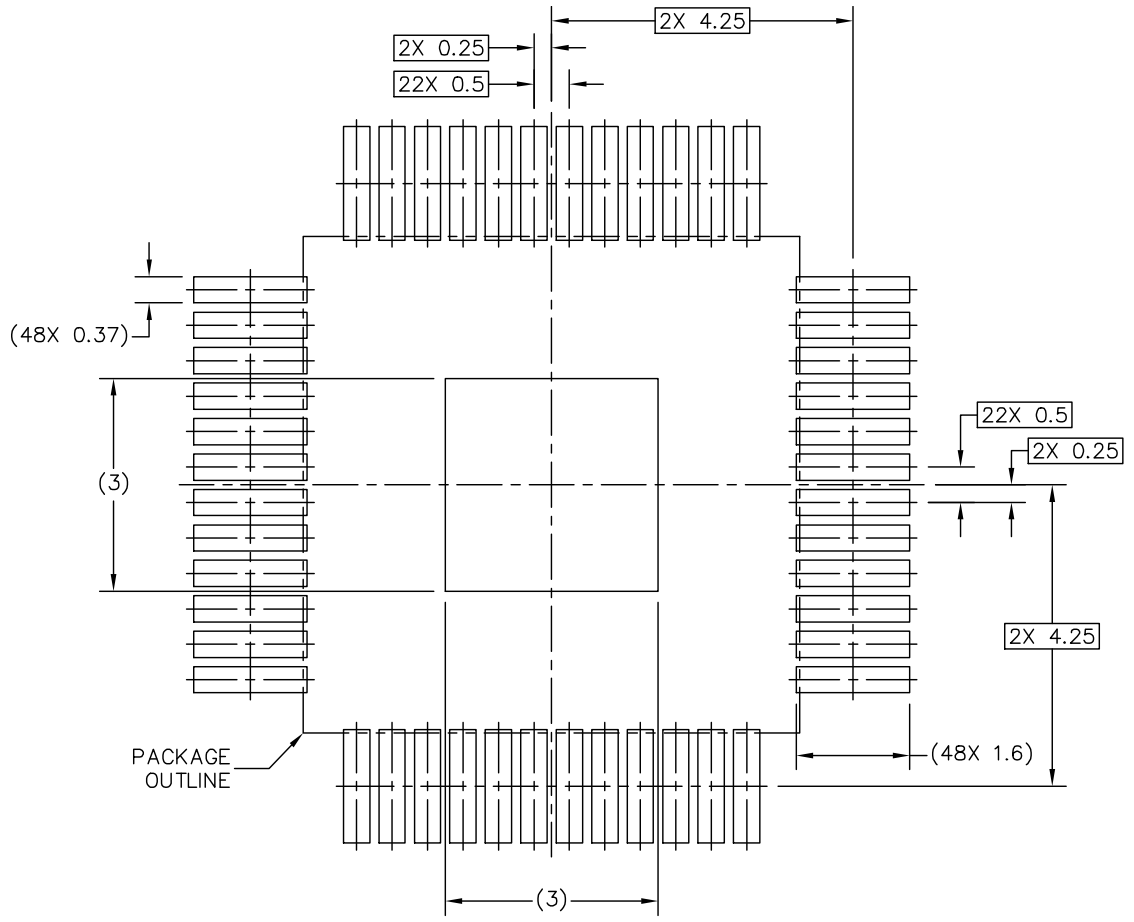


Fig. 3. Package outline note HLQFP48 (SOT1571-7)

3. Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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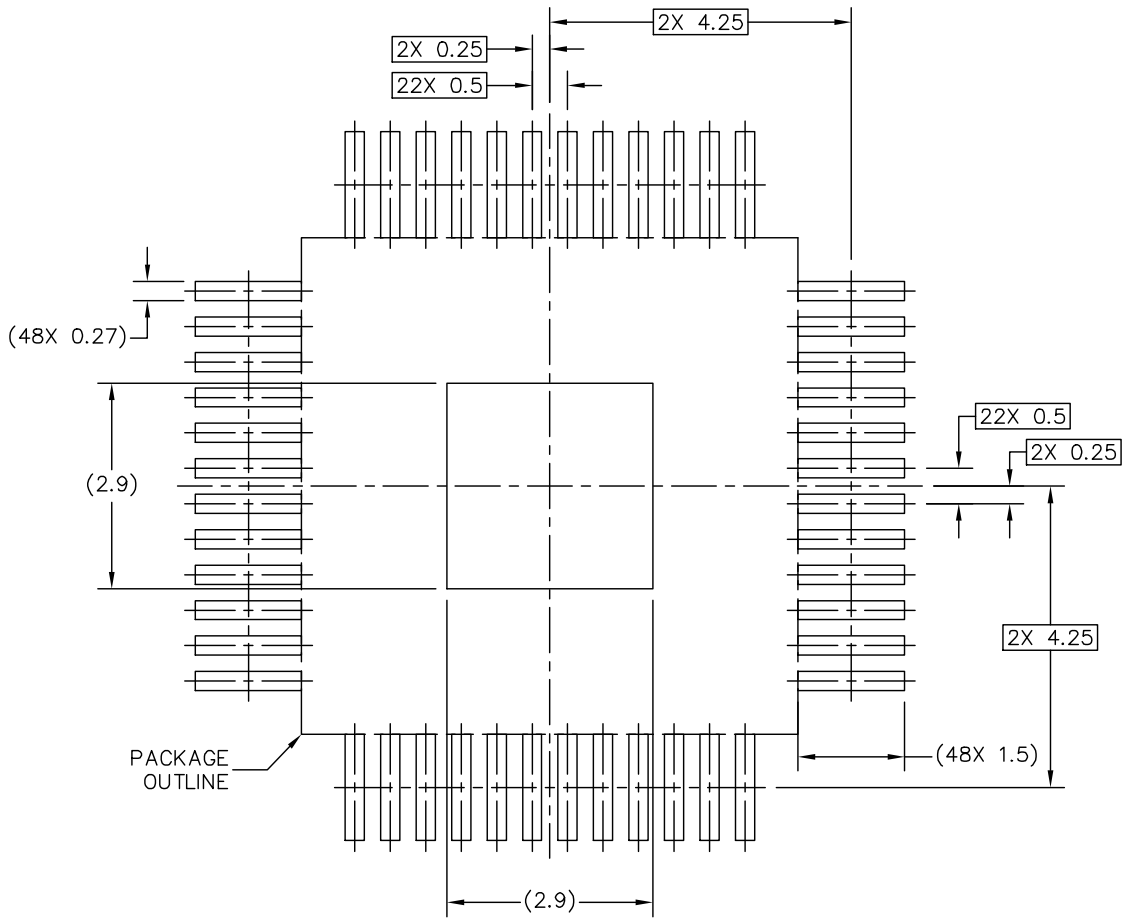
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: JEDEC MS–026 BBC	DRAWING NUMBER: SOT1571–7	REVISION: 0	

Fig. 4. Reflow soldering footprint for SOT1571-7



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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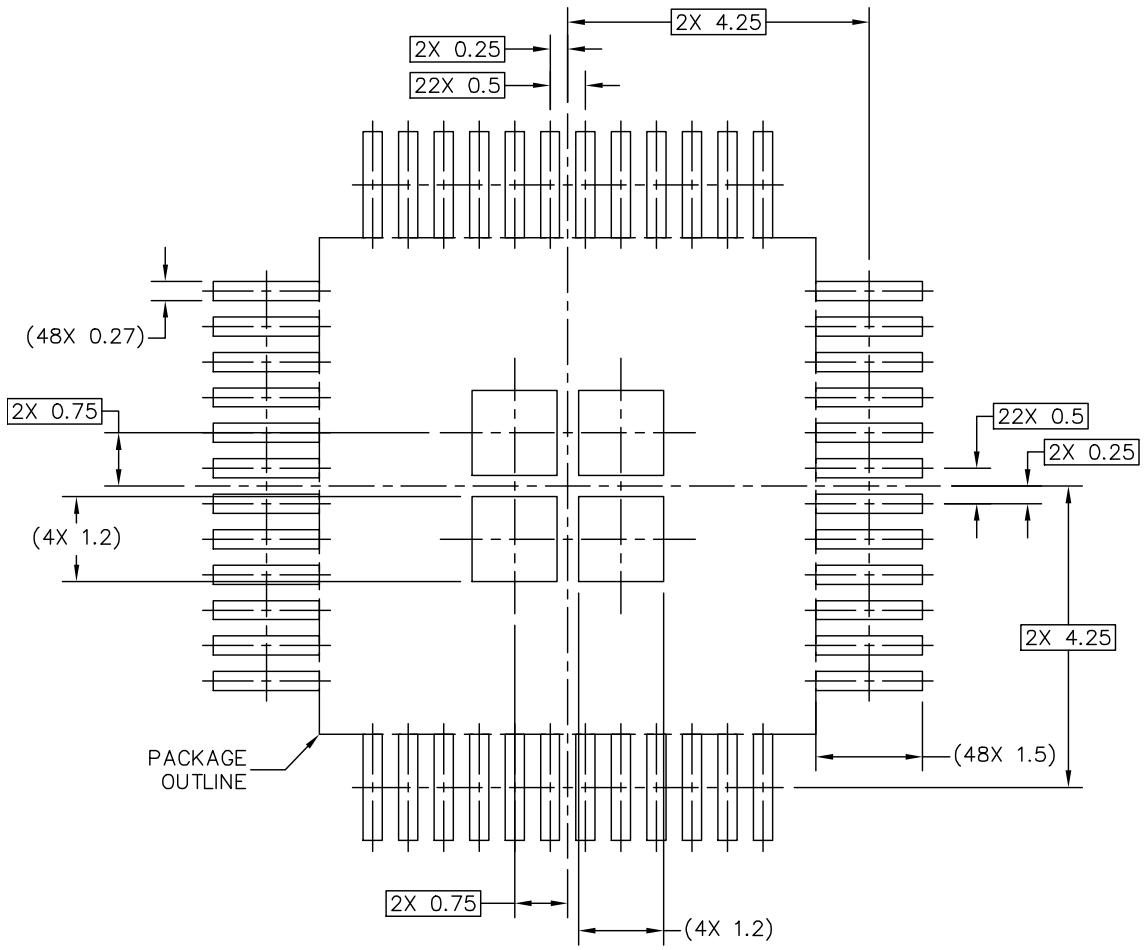
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: JEDEC MS–026 BBC	DRAWING NUMBER: SOT1571–7	REVISION: O	

Fig. 5. Reflow soldering footprint part2 for HLQFP48 (SOT1571-7)



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Fig. 6. Reflow soldering footprint part3 for HLQFP48 (SOT1571-7)

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5. Contents

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Date of release: 14 December 2017